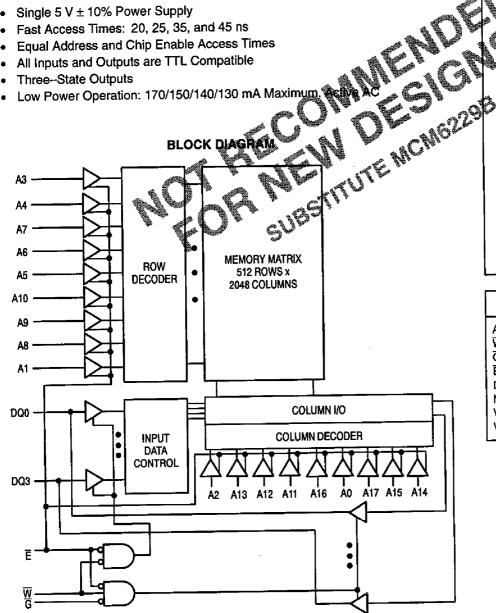
# 256K x 4 Bit Static Random **Access Memory**

The MCM6229A is a 1,048,576 bit static random access memory organized as 262,144 words of 4 bits, fabricated using high-performance silicon-gate CMOS technology. Static design eliminates the need for external clocks or timing strobes, while CMOS circuitry reduces power consumption and provides for greater reliability.

The MCM6229A is equipped with both chip enable  $(\overline{\mathbf{E}})$  and output enable  $(\overline{\mathbf{G}})$ pins, allowing for greater system flexibility and eliminating bus contention prob-

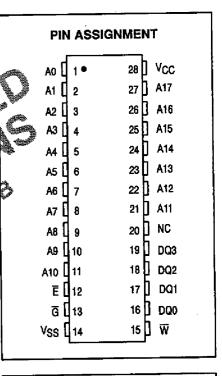
The MCM6229A is available in 400 mil, 28-lead surface-mount SOJ packages.

- Single 5 V ± 10% Power Supply



## MCM6229A





PIN NAMES								
A0 − A17         Address Inputs           ₩         Write Enable           G         Output Enable           E         Chip Enable           DQ0 − DQ3         Data Inputs/Outputs           NC         No Connection           VCC         +5 V Power Supply           VSS         Ground								

#### **TRUTH TABLE**

E	Ğ	W	Mode	I/O Pin	Cycle	Current
Н	Х	Х	Not Selected	High-Z	_	ISB1, ISB2
L	Н	Н	Output Disabled	High-Z	"	ICCA
L	L	Н	Read	D <sub>out</sub>	Read	<sup>I</sup> CCA
L_	Х	L	Write	D <sub>in</sub>	Write	ICCA

H = High, L = Low, X = Don't Care

### ABSOLUTE MAXIMUM RATINGS (See Note)

,		
Symbol	Value	Unit
Vcc	- 0.5 to 7.0	V
V <sub>in</sub> , V <sub>out</sub>	- 0.5 to V <sub>CC</sub> + 0.5	٧
lout	± 20	mA
PD	1.1	w
T <sub>bias</sub>	- 10 to + 85	ç
TA	0 to + 70	°C
Tstg	- 55 to + 150	°C
	V <sub>CC</sub> V <sub>in</sub> , V <sub>out</sub> lout P <sub>D</sub> T <sub>bias</sub> T <sub>A</sub>	VCC         - 0.5 to 7.0           Vin. Vout         - 0.5 to VCC + 0.5           lout         ± 20           PD         1.1           Tbias         - 10 to + 85           TA         0 to + 70

NOTE: Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to RECOMMENDED OPER-ATING CONDITIONS. Exposure to higher than recommended voltages for extended periods of time could affect device reliability.

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to these high-impedance circuits.

This CMOS memory circuit has been designed to meet the dc and ac specifications shown in the tables, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow of at least 500 linear feet per minute is maintained.

## DC OPERATING CONDITIONS AND CHARACTERISTICS

(VCC = 5.0 V  $\pm$  10%, TA = 0 to 70°C, Unless Otherwise Noted)

#### RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min	Max	Unit
Supply Voltage (Operating Voltage Range)	Vcc	4.5	5.5	ν
Input High Voltage	VIH	2.2	V <sub>CC</sub> + 0.3**	V
Input Low Voltage	V <sub>IL</sub>	- 0.5*	0.8	V

<sup>\*</sup> $V_{IL}$  (min) = -0.5 V dc;  $V_{IL}$  (min) = -2.0 V ac (pulse width  $\leq 20$  ns).

#### DC CHARACTERISTICS AND SUPPLY CURRENTS

Symbol	Min	Тур*	Max	Unit
likg(i)	_		± 1	μА
<del>  -                                   </del>	_	<u> </u>	±1	μA
ICCA	  	140 120 110 100	170 150 140 130	mA
ISB1		7	20	mA
I <sub>SB2</sub>	_	4	15	mA
VOL		<del>   </del>	0.4	V
VOH	2.4	<del> </del>	_	V
	ISB1	Ikg(O)	Ikg(O)	Ikg(O)

<sup>\*</sup>Typical measurements are taken at 25°C, V<sub>CC</sub> = 5 V.

<sup>\*\*</sup> $V_{IH}$  (max) =  $V_{CC}$  + 0.3 V dc;  $V_{IH}$  (max) =  $V_{CC}$  + 2 V ac (pulse width  $\leq$  20 ns).

## CAPACITANCE (f = 1.0 MHz, dV = 3.0 V, TA = 25°C, Periodically Sampled Rather Than 100% Tested)

Ch	aracteristic	Symbol	Тур	Max	Unit
Input Capacitance	All Inputs Except Clocks and DQ $\overline{E}$ , $\overline{G}$ , and $\overline{W}$	C <sub>in</sub> C <sub>ck</sub>	4 5	6 8	pF
Input/Output Capacitance	. DQ	CI/O	5	8	pF

## AC OPERATING CONDITIONS AND CHARACTERISTICS

(VCC = 5.0 V  $\pm$  10%, T<sub>A</sub> = 0 to + 70°C, Unless Otherwise Noted)

rement Reference Level 1.5 V
See Figure 1A

#### READ CYCLE TIMING (See Notes 1 and 2)

READ CYCLE TIMING (See Notes 1 ar		6229A-20		6229A-25		6229A-35		6229A-45			[
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Unit	Notes
Read Cycle Time	tavav	20	_	25	_	35		45		ns	2,3
Address Access Time	tavqv	_	20	_	25	_	35		45	ns	
Enable Access Time	†ELQV	_	20		25	<b>—</b>	35		45	ns	4
Output Enable Access Time	tGLQV		8	-	10	_	15	_	15	ns	
Output Hold from Address Change	tAXQX	5	_	5	_	5	<u> </u>	5	_	ns	
Enable Low to Output Active	tELQX	5	T-	5	_	5	_	5		ns	5,6,7
Output Enable Low to Output Active	†GLQX	0	_	0	_	0		O	_	ns	5,6,7
Enable High to Output High–Z	tEHQZ	0	9	0	10	0	12	0	15	ns	5,6,7
Output Enable High to Output High-Z	tGHQZ	0	9	0	10	0	12	0	15	ns	5,6,7
Power Up Time	tELICCH	0	_	0	_	0	_	0	_	ns	
Power Down Time	†EHICCL	T —	20	1-	25	T -	35	T —	45	ns	

#### NOTES:

- 1. W is high for read cycle.
- 2. Product sensitivities to noise require proper grounding and decoupling of power supplies as well as minimization or elimination of bus contention conditions during read and write cycles.
- 3. All timings are referenced from the last valid address to the first transitioning address.
- 4. Addresses valid prior to or coincident with  $\overline{\mathsf{E}}$  going low.
- 5. At any given voltage and temperature, tEHQZ max is less than tELQX min, and tGHQZ max is less than tGLQX min, both for a given device and from device to device.
- 6. Transition is measured  $\pm$  500 mV from steady-state voltage with load of Figure 1B.
- 7. This parameter is sampled and not 100% tested.
- 8. Device is continuously selected ( $\overline{E} \le V_{IL}, \overline{G} \le V_{IL}$ ).

#### **AC TEST LOADS**

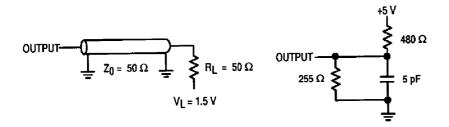


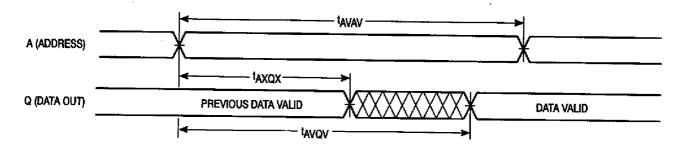
Figure 1A

Figure 1B

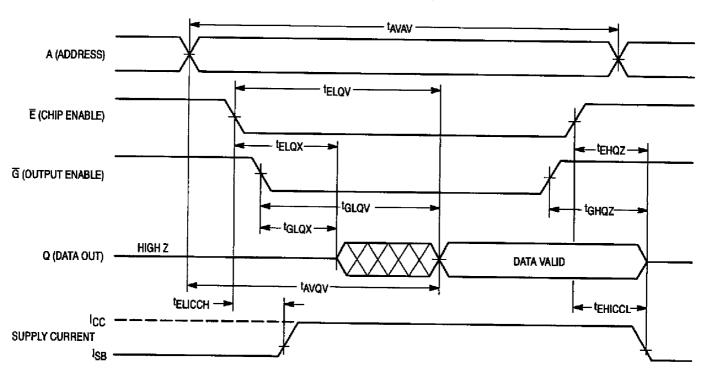
#### **TIMING LIMITS**

The table of timing values shows either a minimum or a maximum limit for each parameter. Input requirements are specified from the external system point of view. Thus, address setup time is shown as a minimum since the system must supply at least that much time (even though most devices do not require it). On the other hand, responses from the memory are specified from the device point of view. Thus, the access time is shown as a maximum since the device never provides data later than that time.

READ CYCLE 1 (See Notes 1, 2, and 8)



## READ CYCLE 2 (See Note 8)

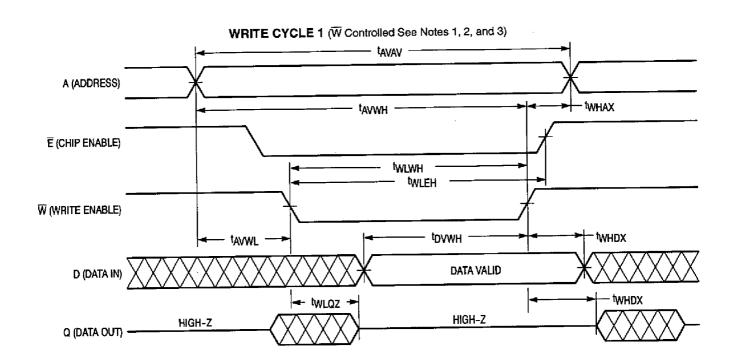


#### WRITE CYCLE 1 (W Controlled, See Notes 1, 2, and 3)

W		6229	9A-20 6229A-25		6229	A-35	6229A-45		] 1	İ	
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Unit	Notes
Write Cycle Time	†AVAV	20		25	_	35	_	45		ns	4
Address Setup Time	tavwl	0	_	0		0	_	0	<u> </u>	ns	
Address Valid to End of Write	tavwh	15		17	_	20		25		กร	
Write Pulse Width	tWLWH,	15	-	17	_	20		25	_	ns	
Data Valid to End of Write	tDVWH	10	_	10	_	15		20	<u> </u>	ns	
Data Hold Time	twHDX	0		0	-	0	_	0		ns	
Write Low to Data High-Z	twLQZ	0	9	0	10	0	15	0	20	ns	5,6,7
Write High to Output Active	twHQX	5		5	_	5	-	5		ns	5,6,7
Write Recovery Time	twhax	0	_	0	-	0		0		nş	<u> </u>

#### NOTES:

- 1. A write occurs during the overlap of  $\overline{E}$  low and  $\overline{W}$  low.
- 2. Product sensitivities to noise require proper grounding and decoupling of power supplies as well as minimization or elimination of bus contention conditions during read and write cycles.
- 3. If  $\overline{G}$  goes low coincident with or after  $\overline{W}$  goes low, the output will remain in a high-impedance state.
- 4. All timings are referenced from the last valid address to the first transitioning address.
- 5. Transition is measured  $\pm$  500 mV from steady-state voltage with load of Figure 1B.
- 6. This parameter is sampled and not 100% tested.
- 7. At any given voltage and temperature, twLQZ max is less than twHQX min both for a given device and from device to device.



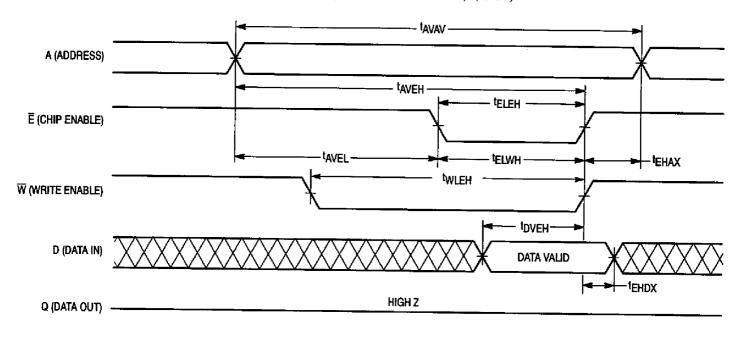
### WRITE CYCLE 2 (E Controlled, See Notes 1, 2, and 3)

	1	6229	A-20	-20 6229A-		6229A-25 6229A-		-35 6229A-45		T	T
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Unit	Notes
Write Cycle Time	†AVAV	20	_	25	_	35		45		ns	4
Address Setup Time	†AVEL	0	_	0		0	_	0		ns	
Address Valid to End of Write	tAVEH	15	-	17		20	_	25	<del>  _</del>	ns	<u> </u>
Enable to End of Write	tELEH, tELWH	15	_	17	_	20	_	25	_	ns	5, 6
Write Pulse Width	tWLEH	15	_	17	_	20		25	_	ns	
Data Valid to End of Write	tDVEH	10	_	10		15		20		ns	
Data Hold Time	tEHDX	0	_	Ō	_	0		0	$\vdash =$	ns	
Write Recovery Time	tEHAX	0	_	0		0	_	0	<u> </u>	ns	

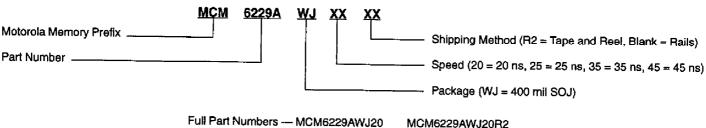
#### NOTES:

- 1. A write occurs during the overlap of  $\overline{E}$  low and  $\overline{W}$  low.
- 2. Product sensitivities to noise require proper grounding and decoupling of power supplies as well as minimization or elimination of bus contention conditions during read and write cycles.
- 3. If  $\overline{G}$  goes low coincident with or after  $\overline{W}$  goes low, the output will remain in a high-impedance state.
- 4. All timings are referenced from the last valid address to the first transitioning address.
- 5. If  $\overline{E}$  goes low coincident with or after  $\overline{W}$  goes low, the output will remain in a high-impedance state.
- 6. If  $\overline{E}$  goes high coincident with or before  $\overline{W}$  goes high, the output will remain in a high-impedance state.

## WRITE CYCLE 2 (E Controlled See Notes 1, 2, and 3)



# ORDERING INFORMATION (Order by Full Part Number)



Full Part Numbers — MCM6229AWJ20 MCM6229AWJ20R2 MCM6229AWJ25R2 MCM6229AWJ35R2 MCM6229AWJ35R2

MCM6229AWJ35 MCM6229AWJ35R2 MCM6229AWJ45 MCM6229AWJ45R2